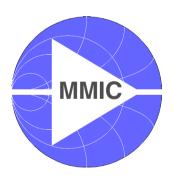
# **BGB420**

# **Active Biased Transistor**



Wireless Silicon Discretes



Edition 2001-08-10
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BGB420 Data sheet

Revision History: 2001-08-10

Previous	Version: 2000-11-28
Page	Subjects (major changes since last revision)
7	S-Parameter table added
8	Figure "Output Compression Point" added
9	SPICE Model added

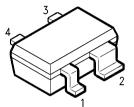
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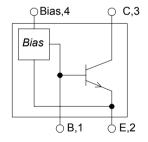
### **BGB420 Active Biased Transistor**

### **BGB420**

### **Features**

- · For high gain low noise amplifiers
- Ideal for wideband applications, cellular telephones, cordless telephones, SAT-TV and high frequency oscillators
- G<sub>ma</sub>=17.5dB at 1.8GHz
- Small SOT343 package
- · Current easy adjustable by an external resistor
- · Open collector output
- Typical supply voltage: 1.4-3.3V
- SIEGET®-25 technology





### Description

SIEGET®-25 NPN Transistor with integrated biasing for high gain low noise figure applications.  $I_C$  can be controlled using  $I_{Bias}$  according to  $I_C$ =10\* $I_{Bias}$ .

**ESD:** Electrostatic discharge sensitive device, observe handling precaution!

Type	Package	Marking	Chip
BGB420	SOT343	MBs	T0514
DOD 120	201010	MIDO	10011



## **Maximum Ratings**

Parameter	Symbol	Value	Unit
Maximum collector-emitter voltage	V <sub>CE</sub>	3.5	V
Maximum collector current	I <sub>C</sub>	30	mA
Maximum bias current	I <sub>Bias</sub>	3	mA
Maximum emitter-base voltage	V <sub>EB</sub>	1.5	V
Maximum base current	I <sub>B</sub>	0.7	mA
Total power dissipation, T <sub>S</sub> < 107°C <sup>1)</sup>	P <sub>tot</sub>	120	mW
Junction temperature	T <sub>j</sub>	150	°C
Operating temperature range	T <sub>OP</sub>	-40+85	°C
Storage temperature range	T <sub>STG</sub>	-65 <b>+</b> 150	°C
Thermal resistance: junction-soldering point	R <sub>th JS</sub>	<270	K/W

### Notes:

For detailed symbol description refer to figure 1.

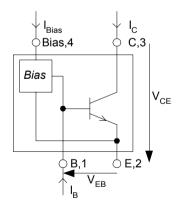


Fig. 1: Symbol definition

 $<sup>^{1)}\,</sup>T_S$  is measured on the emitter lead at the soldering point to the PCB



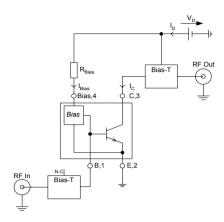


Fig. 2: Test Circuit for Electrical Characteristics and S-Parameter

**Electrical Characteristics** at  $T_A$ =25°C (measured in test circuit specified in fig. 2, min./max. values verified by random sampling)

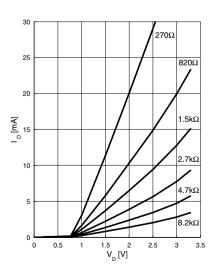
Parameter	Symbol	min.	typ.	max.	Unit	
Maximum available power ga V <sub>D</sub> =2V, I <sub>c</sub> =20mA, f=1.8GHz	G <sub>MA</sub>	16.0	17.5		dB	
Insertion power gain V <sub>D</sub> =2V, I <sub>c</sub> =20mA	f=0.9GHz f=1.8GHz	S <sub>21</sub>   <sup>2</sup>		22 16		dB
Insertion loss V <sub>D</sub> =2V, I <sub>c</sub> =0mA	f=0.9GHz f=1.8GHz	IL		21 15		dB
Noise figure ( $Z_S$ =50 $\Omega$ ) V <sub>D</sub> =2V, I <sub>c</sub> =5mA	f=0.9GHz f=1.8GHz	F <sub>50Ω</sub>		1.3 1.5	1.8 2.0	dB
Output power at 1dB gain cor V <sub>D</sub> =2V, I <sub>c</sub> =20mA, f=1.8GHz	mpression $Z_L = Z_{LOPT}$ $Z_L = 50\Omega$	P <sub>-1dB</sub>	7	12 10		dBm
Output third order intercept po V <sub>D</sub> =2V, I <sub>c</sub> =20mA, f=1.8GHz	oint $Z_{L/S}=Z_{L/SOPT}$ $Z_{L/S}=50\Omega$	OIP <sub>3</sub>	17	22 20		dBm
Collector-base capacitance V <sub>CB</sub> =2V, f=1MHz		C <sub>CB</sub>		0.16		pF
Current Ratio $I_C/I_{Bias}$ $I_{Bias}$ =0.5mA, $V_D$ =3V		CR	7	10	13	



# **S-Parameter** $V_D$ =2V, $I_C$ =20mA (see Electrical Characteristics for conditions)

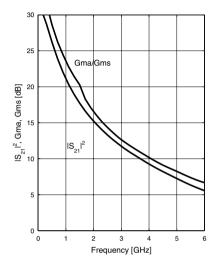
Frequency	S11	S11	S21	S21	S12	S12	S22	S22
[GHz]	Mag	Ang	Mag	Ang	Mag	Ang	Mag	Ang
0.1	0.4412	-24.8	35.7070	160.6	0.0078	83.5	0.9225	-14.1
0.2	0.4064	-47.4	31.7670	143.9	0.0157	77.5	0.8321	-26.2
0.4	0.3261	-81.6	23.1980	120.9	0.0261	70.9	0.6380	-41.4
0.6	0.2854	-105.8	17.2590	106.9	0.0351	69.4	0.5012	-49.6
0.8	0.2615	-124.2	13.5050	97.5	0.0444	68.9	0.4100	-54.2
1.0	0.2525	-136.4	10.9810	90.6	0.0537	68.2	0.3435	-57.4
1.2	0.2505	-148.9	9.1940	84.8	0.0628	67.3	0.2946	-60.2
1.4	0.2476	-158.2	7.8930	80.1	0.0720	65.9	0.2571	-62.6
1.6	0.2533	-167.1	6.9070	75.6	0.0819	64.6	0.2228	-64.2
1.8	0.2579	-173.3	6.1460	71.7	0.0915	62.9	0.1966	-66.0
2.0	0.2584	-178.7	5.5300	68.2	0.1009	61.4	0.1751	-66.3
3.0	0.2874	157.6	3.6990	51.6	0.1495	51.7	0.0802	-70.1
4.0	0.3505	139.0	2.7770	36.1	0.1970	40.4	0.0366	-178.8
5.0	0.4061	125.9	2.1930	21.5	0.2392	29.4	0.0913	126.7
6.0	0.4450	117.1	1.8050	8.6	0.2864	18.9	0.1340	99.8

# **Device Current** $I_D = f(V_D, R_{Bias})$

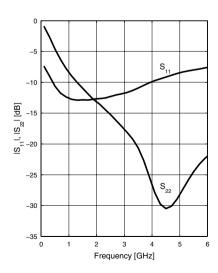




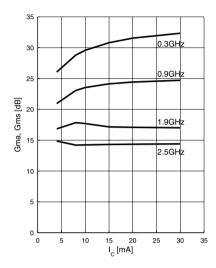
# $\begin{array}{l} \textbf{Power Gain} \ |\textbf{S}_{21}|^2, \ \textbf{Gma}, \ \textbf{Gms=f(f)} \\ \textbf{V}_{\textbf{D}} = 3\textbf{V}, \ \textbf{I}_{\textbf{C}} = 20 \text{mA} \end{array}$



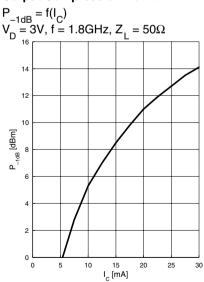
# $\begin{aligned} & \textbf{Matching} \ |S_{11}|, |S_{22}| = f(f) \\ & V_D = 3V, \ I_C = 20 \text{mA} \end{aligned}$



# **Power Gain** Gma, Gms= $f(I_C)$ $V_D = 3V$



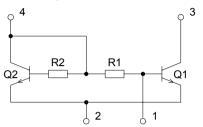
# **Output Compression Point**





# **SPICE Model**

### BGB420-Chip



Q1	T502
Q2	T502 (area factor: 0.1)
R1	2.7kΩ
R2	27kΩ

# Transistor Chip Data T502 (Berkley-SPICE 2G.6 Syntax)

### .MODEL T502 NPN(

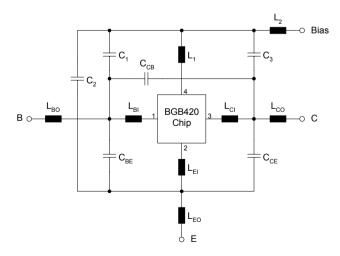
	`	
+ IS = 2.0045e-16	E	3F = 72.534
+ IKF = 0.48731	I.	SE = 1.9049e-14
+ NR = 1.3325	\	/AR = 19.705
+ NC = 1.1724	F	RB = 8.5757
+ RE = 0.31111	F	RC = 0.10105
+ MJE = 0.46576	Т	F = 6.7661e-12
+ ITF = 0.001	F	PTF = 0
+ MJC = 0.30232	>	(CJC = 0.3
+ VJS = 0.75	N	/JS = 0
+ XTI = 3	F	C = 0.73234

NF = 1.2432
NE = 2.0518
IKR = 0.69141
IRB = 0.00072983
CJE = 1.8063e-15
XTF = 0.42199
CJC = 2.3453e-13
TR = 2.3249e-09
XTB = 0

VAF = 28.383 BR = 7.8287 ISC = 1.9237e-17 RBM = 3.4849 VJE = 0.8051 VTF = 0.23794 VJC = 0.81969 CJS= 0

EG = 1.11

# Package Equivalent Circuit



L <sub>BI</sub>	0.36	nΗ
L <sub>B0</sub>	0.4	nΗ
L <sub>EI</sub>	0.3	nΗ
L <sub>EO</sub>	0.15	nΗ
L <sub>CI</sub>	0.36	nΗ
L <sub>co</sub>	0.4	nΗ
L <sub>1</sub>	0.6	nΗ
L <sub>2</sub>	0.4	nΗ
C <sub>BE</sub>	95	fF
C <sub>CB</sub> C <sub>CE</sub>	6	fF
C <sub>CE</sub>	132	fF
C <sub>1</sub>	28	fF
C <sub>2</sub>	88	fF
C <sub>3</sub>	8	fF

Valid up to 3GHz



# **Typical Application**

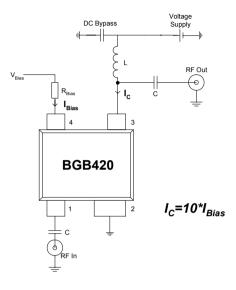
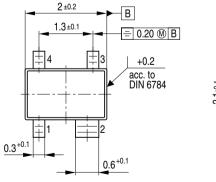
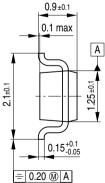


Fig. 3: Typical application circuit. This proposal demonstrates how to use the BGB420 as a Self-Biased Transistor. As for a discrete Transistor matching circuits have to be applied. A good starting point for various applications are the Application Notes provided for the BFP420.

### **Package Outline**





GPS05605